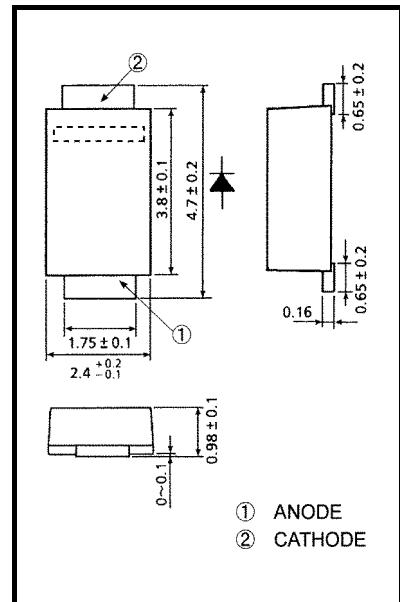


- Forward voltage: $V_{FM} = 0.40$ V (max)
- Average forward current: $I_F (AV) = 3.0$ A
- Repetitive peak reverse voltage: $V_{RRM} = 30$ V
- Suitable for compact assembly due to small surface-mount package "M-FLAT™"

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	30	V
Average forward current	$I_F (AV)$	3.0 (Note 1)	A
Peak one cycle surge forward current (non-repetitive)	I_{FSM}	40 (50 Hz)	A
Junction temperature	T_j	-40~125	°C
Storage temperature	T_{stg}	-40~150	°C



Weight: 0.023 g (typ.)

Note 1: $T_\ell = 89.2^\circ\text{C}$: Rectangular waveform ($\alpha = 180^\circ$), $V_R = 15$ V

Note 2: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Electrical Characteristics ($T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Peak forward voltage	V_{FM} (1)	$I_{FM} = 0.5$ A	—	0.27	—	V
	V_{FM} (2)	$I_{FM} = 1.0$ A	—	0.30	—	
	V_{FM} (3)	$I_{FM} = 3.0$ A	—	0.37	0.40	
Repetitive peak reverse current	I_{RRM}	$V_{RRM} = 5$ V	—	0.05	—	mA
	I_{RRM}	$V_{RRM} = 30$ V	—	0.07	0.5	
Junction capacitance	C_j	$V_R = 10$ V, $f = 1.0$ MHz	—	170	—	pF
Thermal resistance	R_{th} (j-a)	Device mounted on a ceramic board (soldering land: 2 mm × 2 mm)	—	—	60	°C/W
		Device mounted on a glass-epoxy board (soldering land: 6 mm × 6 mm)	—	—	135	
	R_{th} (j-t)	—	—	—	16	

Marking

Abbreviation Code	Part No.
S2	CMS02

Standard Soldering Pad

Unit: mm

